

ABSTRACT OF THE DISCLOSURE

Embodiments of the invention generally provide a method and plating solution for reducing the degradation of additives in electroplating solutions. The method generally includes adding an anti-oxidant to the electroplating solution in an amount effective to reduce the degradation of additives in the plating solution. The plating solution generally includes copper ions, at least one organic plating additive, and at least one anti-oxidant in an amount sufficient to reduce the degradation of the organic plating additives in the plating solution.

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